

**REMARKS**

The Applicants request reconsideration of the rejection.

Claims 32 and 34-43 are now pending.

Claim 33 was rejected under 35 U.S.C. §112, first and second paragraphs, as set forth on pages 2-3 of the Office Action. Without admitting to the propriety of these rejections, Claim 33 has been canceled without prejudice to expedite examination of the remaining claims.

Claims 31-34, 36-37, 39-40 and 43 were rejected under 35 U.S.C. §103(e) as being anticipated by Tanaka et al, U.S. 6,265,762. The same claims were rejected under 35 U.S.C. §102(e) as being anticipated by Fogal et al., U.S. 5,177,032 (Fogal). The Applicants traverse as follows.

As claimed in the remaining independent Claim 32, the present invention is directed to a semiconductor device having a plurality of inner leads extending around a semiconductor chip, and an insulating member supporting the semiconductor chip and joined to an end portion of the inner leads of the respective inner leads, wherein surface electrodes of the semiconductor chip are connected to the inner leads by conductive wires, and wherein an arrangement pitch of the

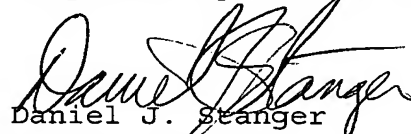
surface electrodes is no more than one half as great as a minimum of a tip pitch between the inner leads that are adjacent to each other. By these features, the inventive semiconductor device is less susceptible to "wire flow" and inner lead "flopping" caused by, for example, flow of the mold resin due to fixing of the inner leads to the insulating member. As a result, the semiconductor devices have enhanced reliability and effectiveness compared to those of the prior art.

Both Tanaka and Fogal are directed to structures in which end portions of the inner leads and a plate-shaped member are joined, but there is neither a teaching nor a suggestion that a pad pitch (a pitch of the surface electrodes) is no more than one half the lead pitch of the inner leads. In particular, against this limitation, the Examiner cites Tanaka's Figures 6 and 16 which show views for wire bonding, but which teach nothing about the relative pitches of the semiconductor surface electrodes and the inner leads. Similarly, Fogal's Figure 3 does not suggest this limitation to the person of ordinary skill in the art. Accordingly, neither Tanaka nor Fogal discloses the invention.

Claims 35, 38, and 42 were rejected under 35 U.S.C. §103(a) as being unpatentable over Fogal in view of Newman, U.S. 5,068,708. Claim 41 was rejected under 35 U.S.C. §103(a) as being unpatentable over Fogal in view of Templeton et al., U.S. 5,457,340. Neither Newman nor Templeton, however, discloses the limitation discussed above relating the surface electrode pitch to the inner lead pitch. Accordingly, no combination of Fogal and either of these secondary references can be said to lead the person of ordinary skill to the invention.

In view of the foregoing amendments and remarks, the Applicants request reconsideration of the rejection and allowance of the claims.

Respectfully submitted,



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